Abstract

Semiconductor wafer and process for producing said semiconductor wafer

The invention relates to a semiconductor wafer which has an edge region but does not have any defects larger than or equal to 0.3 μm.

Furthermore, the invention relates to a process for producing a semiconductor wafer, comprising the following process sequence: (a) providing a semiconductor wafer having a rounded and etched edge; (b) polishing the edge of the semiconductor wafer, in which step the semiconductor wafer, which is held on a centrally rotating chuck and projects beyond the chuck and at least one polishing drum, which is inclined by a specific angle with respect to the chuck, rotates centrally and is covered with a polishing cloth are moved toward one another and pressed onto one another under a specific contact pressure with a polishing abrasive being supplied continuously; (c) cleaning the semiconductor wafer; (d) inspecting an edge region of the semiconductor wafer using an inspection unit; (e) further processing the semiconductor wafer.